

Silicon Schottky Barrier Diode

Features

- Low leakage current
- Small Surface Mounting Type
- Ideal for Automated Placement
- Ultrafast Reverse Recovery Time
- Low Forward Voltage Drop
- High Surge Capability
- RoHS Compliant

Applications

- Rail to rail ESD protection
- Overshoot and undershoot switching control
- Mobile phones and accessories
- Video game consoles connector ports
- Free Wheelin

Mechanical Characteristics

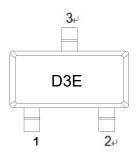
- Package: SOT-23
- Ideal for Automated Placement
- Case Material: "Green" Molding Compound
- UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 3 per J-STD-020





Marking: D3E

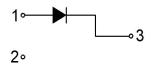
SOT-23







Epuivalent circuit





| Absolute Maximum Ratings (TA=25°C unless otherwise noted) | | | |
|---|---------------------|------------|------|
| Parameter | Symbol | Limit | Unit |
| Reverse Voltage (Repetitive Peak) | V _{RRM} | 40 | V |
| Reverse Voltage (RMS) | V _{R(RMS)} | 28 | V |
| DC reverse voltage | V _R | 20 | V |
| Continuous Forward Current | Ιο | 500 | mA |
| Non-RepetitivePeakForwardSurge Current@t=8.3ms | I _{FSM} | 3 | А |
| Power Dissipation | P _D | 200 | mW |
| Thermal Resistance Junction to Ambient(Typ) | R _{θJA} | 500 | °C/W |
| Junction Temperature | TJ | -55 ~ +125 | °C |
| Storage Temperature | T _{STG} | -55 ~ +150 | °C |

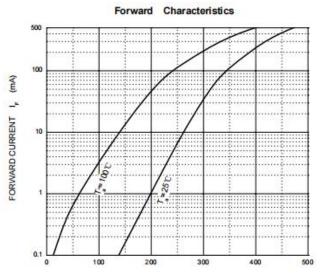
| Electrical Specifications (TA=25°C unless otherwise noted) | | | | | | |
|--|----------------|-----------------------|-----|-----|-----|------|
| Parameter | Symbol | Test Conditions | Min | Тур | Max | Unit |
| Breakdown Voltage | V_{BR} | I _R =100uA | 20 | | | V |
| Reverse Current | I _R | V _R =10V | | | 30 | uA |
| Capacitance between terminals | CT | VR=10V,f=1MHz | | 20 | | pF |
| Forward Voltage | VF | I _F =10mA | | | 0.3 | V |
| | | I _F =500mA | | | 0.5 | V |



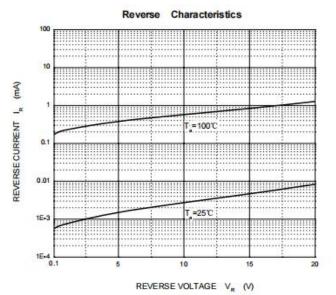
RB411D GOOD-ARKElectronics

Ratings and Characteristics Curves

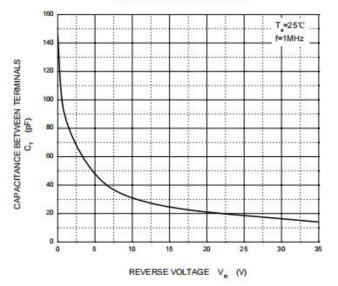
(TA = 25°C unless otherwise noted)



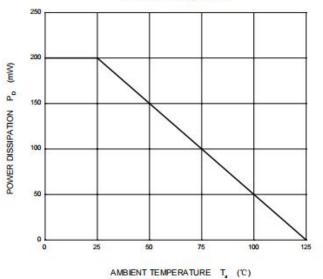
FORWARD VOLTAGE V, (mV)



Capacitance Characteristics



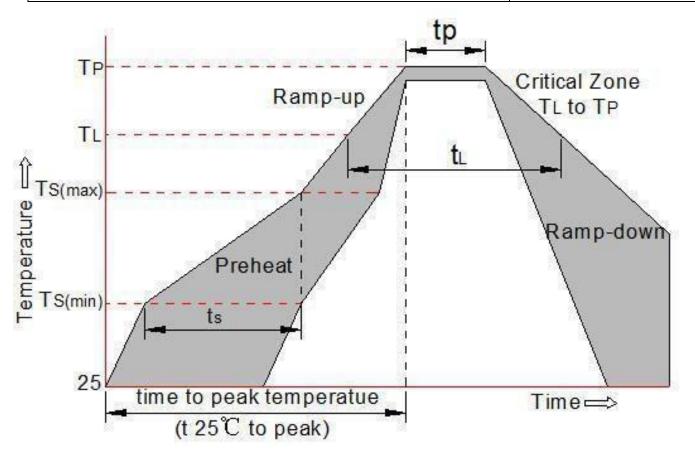
Power Derating Curve





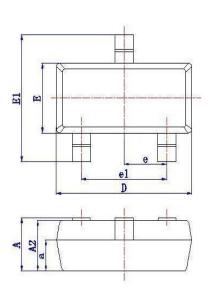
Soldering Parameters

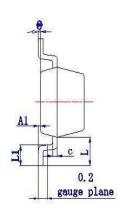
| Reflow Condition | | Pb -Free assembly (see as bellow) |
|---|---|--------------------------------------|
| | -Temperature Min (T _{s(min)}) | +150 ℃ |
| Pre Heat | -Temperature Max(T s(max)) | +200 ℃ |
| | -Time (Min to Max) (ts) | 60 -180 secs. |
| Average | ramp up rate (Liquid us Temp (T L) to peak) | 3 ℃ /sec. Max |
| | Ts(maxt)o T L- Ramp -up Rate | 3 ℃ /sec. Max |
| | -Temperature(T L) (Liquidus) | +217 ℃ |
| Reflow | -Temperature(t L) | 60 -150 secs. |
| Peak Temp (T p) | | +260(+0/ -5) ℃ |
| Time within 5 $^\circ\!\mathrm{C}$ of actual Peak Temp (tp) | | 30 secs. Max |
| Ramp -down Rate | | 6 ℃ /sec. Max |
| Time 25 $^\circ \!\!\! \mathbb{C}$ to Peak Temp (T P) | | 8 min. Max |
| Do not exceed | | +260 ℃ |





Package Outline Dimensions in inches (millimeters)





| | Dimensional | | |
|--------|-------------|------|--|
| Symbol | Millimeters | | |
| | min | max | |
| A | 0.9 | 1.15 | |
| A1 | 0 | 0.1 | |
| A2 | 0.9 | 1.05 | |
| а | (0.6) | | |
| D | 2.8 | 3.0 | |
| E | 1.2 | 1.4 | |
| E1 | 2.25 | 2.55 | |
| е | (0.95) | | |
| e1 | 1.8 | 2.0 | |
| b | 0.3 | 0.5 | |
| С | 0.08 | 0.15 | |
| L | (0.55) | | |
| L1 | 0.3 | 0.5 | |
| θ | 0° | 8° | |

Revision History

| Document Version | Date of release | Description of changes |
|------------------|-----------------|------------------------|
| Rev.A | 2022.05.10 | First issue |
| | | |
| | | |



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